

TELEFUNKEN Semiconductors

BUD86 • BUD87

Silicon NPN High Voltage Switching Transistor

Features

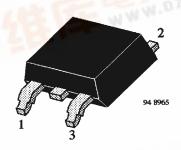
- Multi diffusion technology
- Glass passivation

- High reverse voltage
- Short switching times

Applications

Electronic lamp ballast circuits Switch-mode power supplies





BUD86 BUD87 1 Emitter 2 Collector 3 Base

BUD86 -SMD BUD87 -SMD 1 Emitter 2 Collector 3 Base

Absolute Maximum Ratings

T_{case} = 25°C, unless otherwise specified

Parameter	Test Conditions	Type	Symbol	Value	Unit
Collector-emitter voltage		BUD86	V _{CEO}	400	V
-		BUD87	V _{CEO}	450	V
		BUD86	V _{CES}	800	V
		BUD87	V _{CES}	1000	V
Emitter-base voltage	167		V _{EBO}	5	V
Collector current	-1 35 TUTT	the state of	I_{C}	0.5	Α
Collector peak current	750.00		I _{CM}	1	A
Base current	M.A.		I_{B}	0.3	A
CO 214 1-4			$-I_{\mathbf{B}}$	0.3	A
Total power dissipation	$T_{\rm case} \leq 60^{\circ} {\rm C}$		P _{tot}	20	W
Junction temperature			Tj	150	°C
Storage temperature range			T _{stg}	-65 to +150	°C

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Maximum Thermal Resistance

 $T_{case} = 25$ °C, unless otherwise specified

Parameter	Test Conditions	Symbol	Value	Unit
Junction case		R_{thJC}	4.5	K/W

Electrical Characteristics

T_{case} = 25°C, unless otherwise specified

Parameter	Test Conditions	Type	Symbol	Min	Тур	Max	Unit
Collector cut-off current	$V_{CE} = 800 \text{ V}$	BUD86	I _{CES}			100	μΑ
	$V_{CE} = 1000 \text{ V}$	BUD87	I _{CES}			100	μΑ
	$V_{CE} = 800 \text{ V}; T_{case} = 125 ^{\circ}\text{C}$	BUD86	I _{CES}			1	mA
	$V_{CE} = 1000 \text{ V};$ $T_{case} = 125 ^{\circ} \text{C}$	BUD87	I _{CES}			1	mA
Collector-emitter break-	$I_C = 100 \text{ mA}; L = 125 \text{ mH};$	BUD86	V _{(BR)CEO}	400			V
down voltage (figure 1)	$I_{\text{measure}} = 50 \text{ mA}$	BUD87	V _{(BR)CEO}	450			V
Emitter-base breakdown voltage	$I_E = 1 \text{ mA}$		V _{(BR)EBO}	5			V
Collector-emitter saturation voltage	$I_C = 100 \text{ mA}; I_B = 10 \text{ mA}$		V _{CEsat}			0.8	V
	$I_C = 200 \text{ mA}; I_B = 20 \text{ mA}$		V _{CEsat}			1	V
Base-emitter saturation voltage	$I_C = 200 \text{ mA}; I_B = 20 \text{ mA}$		V _{BEsat}			1	V
DC forward current transfer ratio	$V_{CE} = 5 \text{ V}; I_{C} = 50 \text{ mA}$		h _{FE}		50		
Gain bandwidth product	$I_C = 50 \text{ mA}; V_{CE} = 10 \text{ V};$ f = 1 MHz		f_{T}		20		MHz

Switching Characteristics

 $T_{case} = 25$ °C, unless otherwise specified

Parameter	Test Conditions	Туре	Symbol	Min	Тур	Max	Unit
Resistive load (figure 2)							
Storage time	$I_C = 400 \text{ mA}; I_{B1} = 20 \text{ mA};$		t _s			3.5	μs
Fall time	$-I_{B2} = 40 \text{ mA}; V_S = 125 \text{ V}$		$t_{ m f}$		0.4		μs

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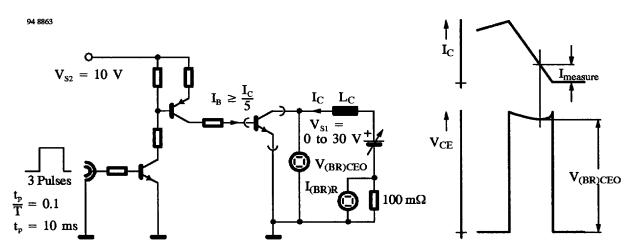


Figure 1. Test circuit for V_{(BR)CE0}

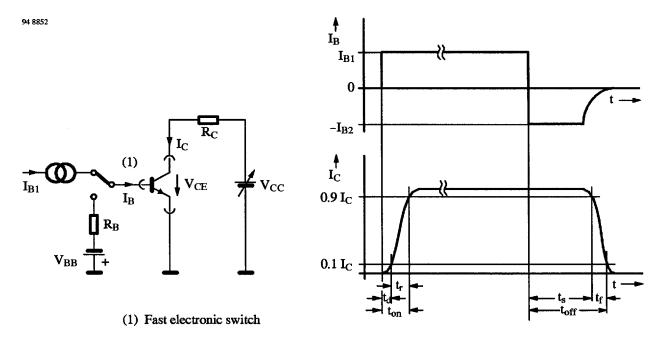


Figure 2. Test circuit for switching characteristics - resistive load

Typical Characteristics ($T_{case} = 25^{\circ}C$ unless otherwise specified)

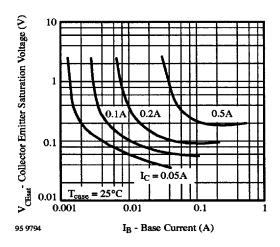


Figure 3. V_{CEsat} vs. I_B

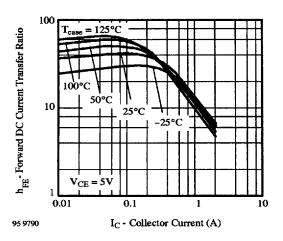


Figure 4. hFE vs. IC

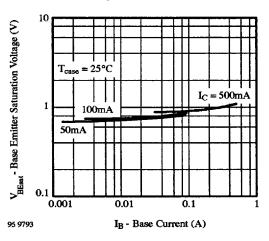


Figure 5. V_{BEsat} vs. I_B

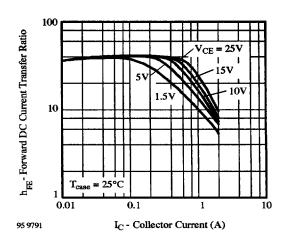
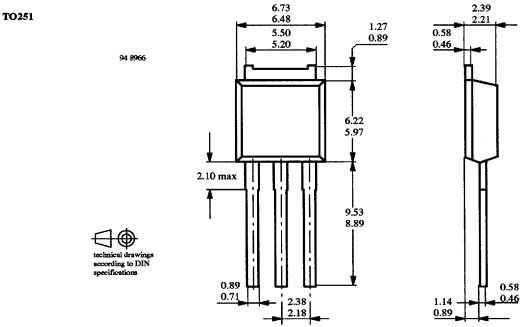
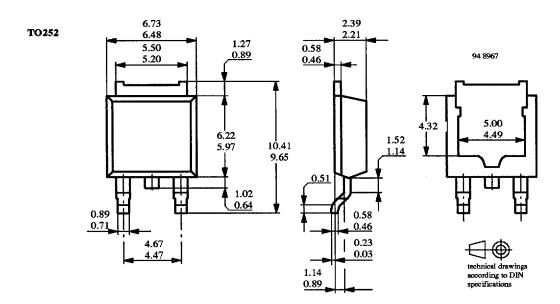


Figure 6. hFE vs. IC

Dimensions in mm





For ordering TO 252 add SMD to the type number (i.e. BUD86-SMD)